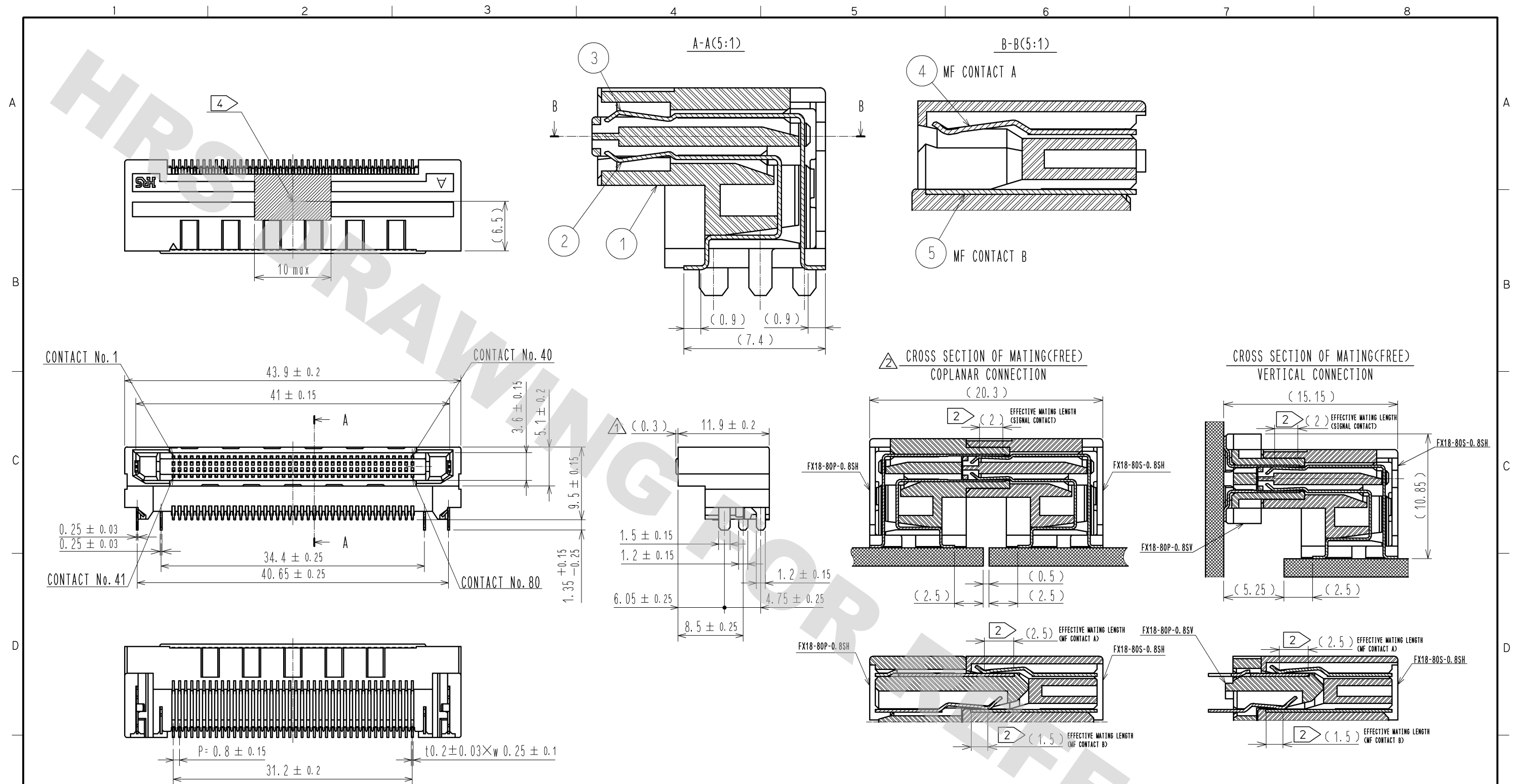


DRAWING F
08/11/2012



NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.

2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)
WHEN USING THIS SEQUENTIAL STRUCTURE. PLEASE AVOID ANGLED INSERTION.

3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)

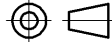
4 IT SHOWS CONNECTOR'S CENTRE OF GRAVITY AND VACUUM PICKUP AREA.

5 THIS IS PACKAGED IN TRAY. (50psc/TRAY)

6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.

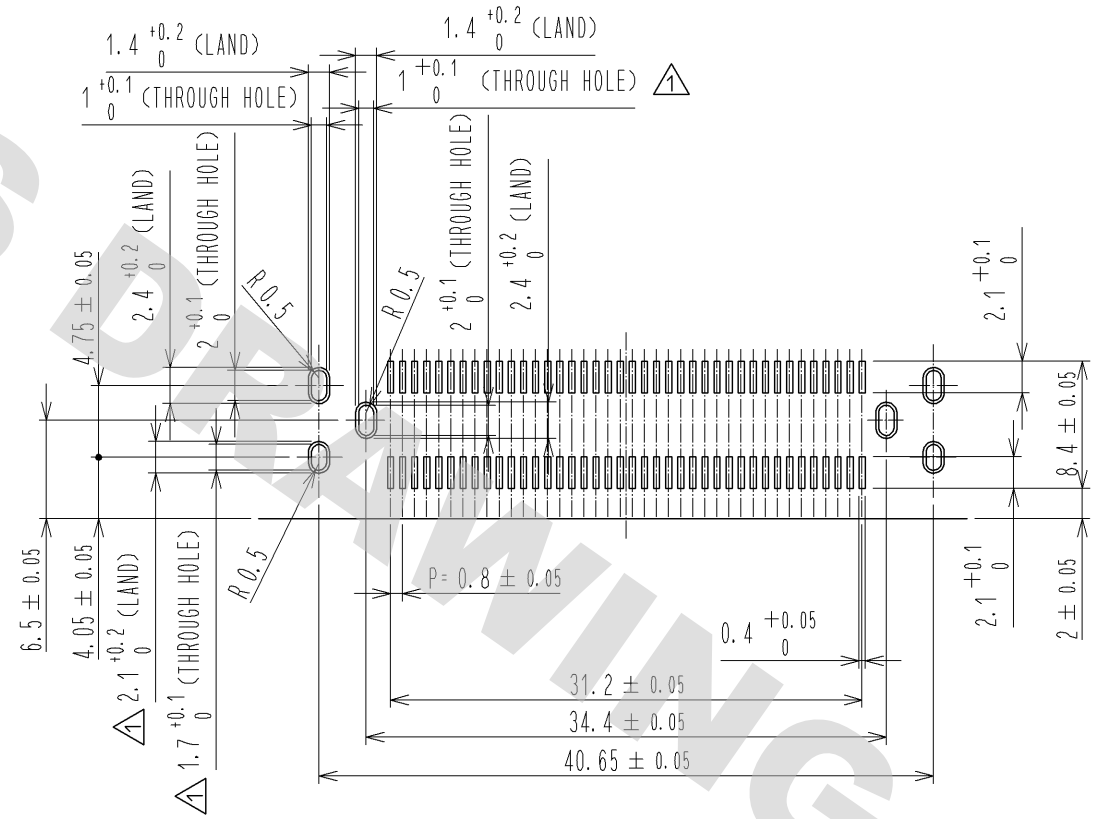
7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1#m	6	POLYSTYRENE	
		LEAD AREA:GOLD 0.03#m			CONTACT AREA:GOLD 0.1#m
		UNDER PLATING:NICKEL 1.3#m	5	PHOSPHOR BRONZE	LEAD AREA:TIN-PLATING 1#m
2	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1#m			UNDER PLATING:NICKEL 1.3#m
		LEAD AREA:GOLD 0.03#m			CONTACT AREA:GOLD 0.1#m
		UNDER PLATING:NICKEL 1.3#m	4	PHOSPHOR BRONZE	LEAD AREA:TIN-PLATING 1#m
1	POLYAMIDE	BLACK UL94V-0			UNDER PLATING:NICKEL 1.3#m
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS

UNITS mm		SCALE 2 : 1	COUNT  1	DESCRIPTION OF REVISIONS DIS-F-005993	DESIGNED TH. SANO	CHECKED KI. HIROKAWA	DATE 12. 01. 27
 HIROSE ELECTRIC CO., LTD.				APPROVED :HS. OKAWA 10. 06. 16 CHECKED :KI. HIROKAWA 10. 06. 16 DESIGNED :TH. SANO 10. 06. 16 DRAWN :TH. SANO 10. 06. 16			
				DRAWING NO. EDC3-159083-00 PART NO. FX18-80S-0. 8SH CODE NO. CL579-0011-6-00			
				 1/2			

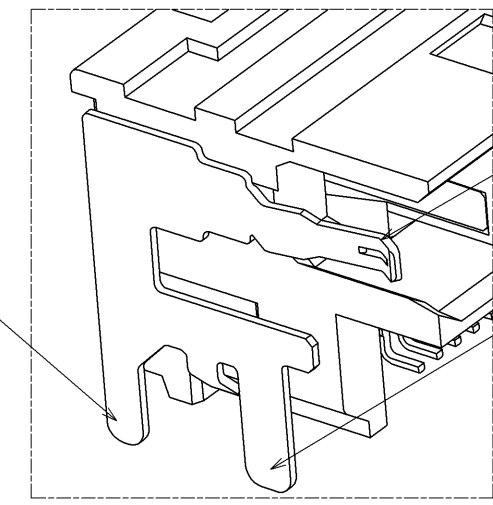
DRAWING FOR REFERENCE: This is subject to change without notice
08/11/2012

RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
(PCB THICKNESS: $t=1.6\text{mm}$ METAL MASK THICKNESS: $t=0.12\text{mm}$)

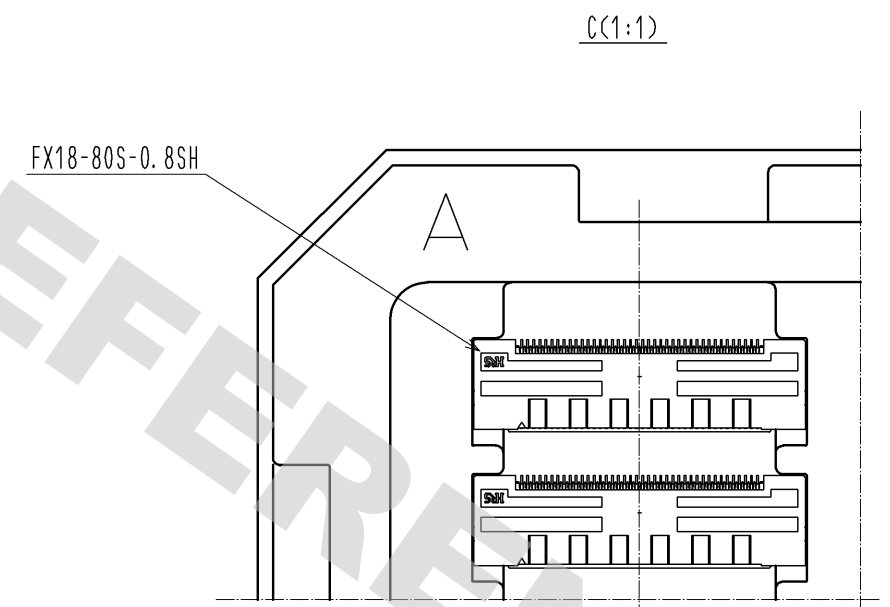
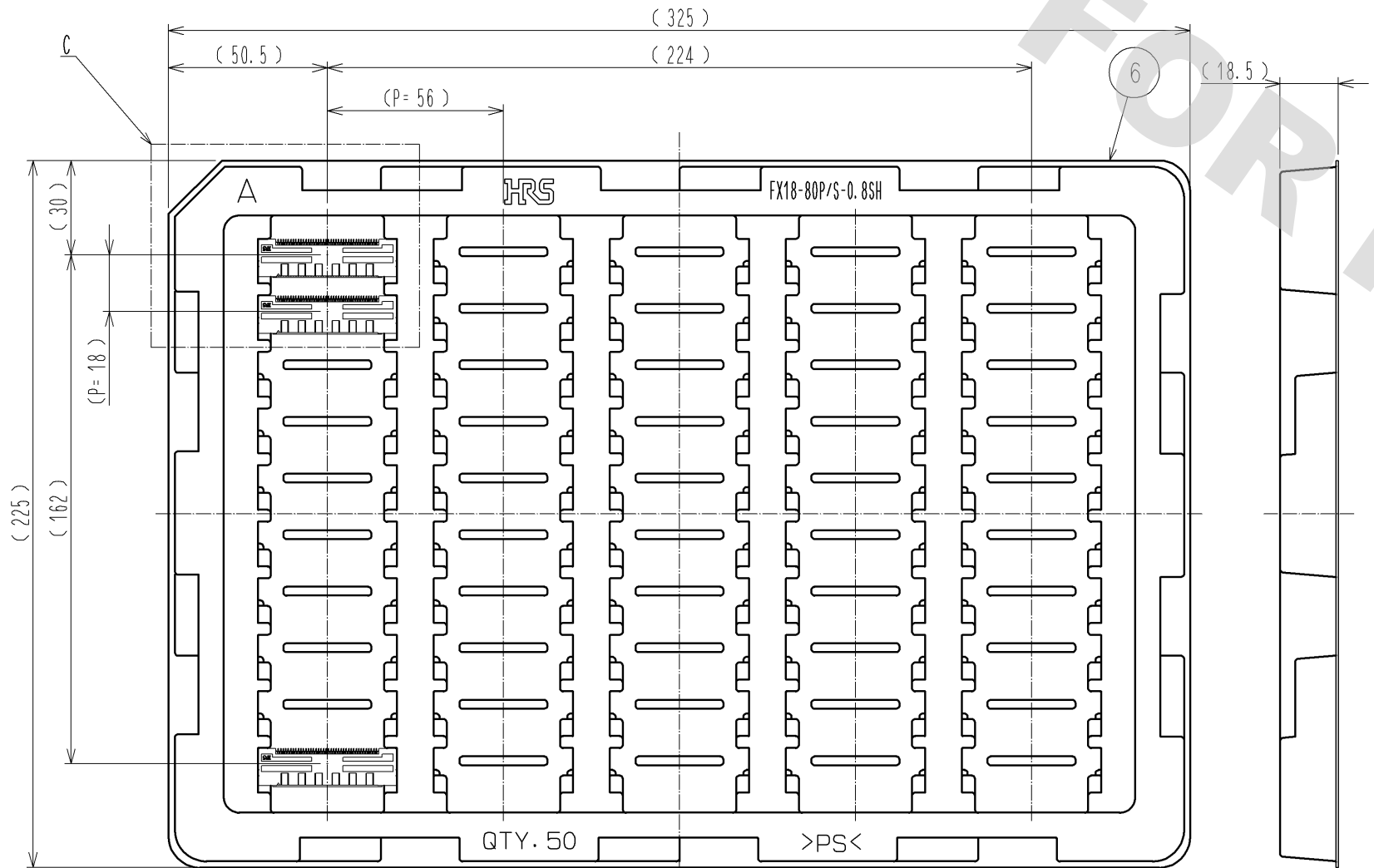


5 DRAWING FOR PACKING(1:2)

1 8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.
BE SURE TO CONNECT TO THE SAME CIRCUIT.



HRS	DRAWING NO.	EDC3-159083-00	2/2
	PART NO.	FX18-80S-0.8SH	
	CODE NO.	CL579-0011-6-00	